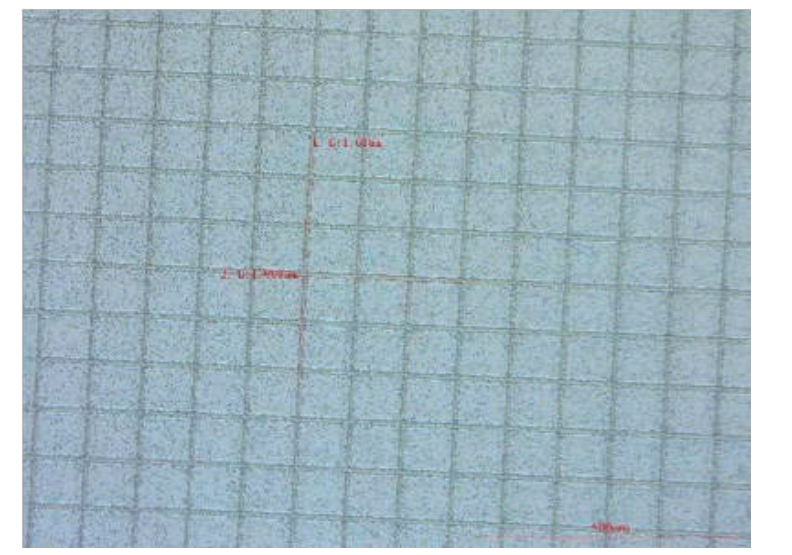
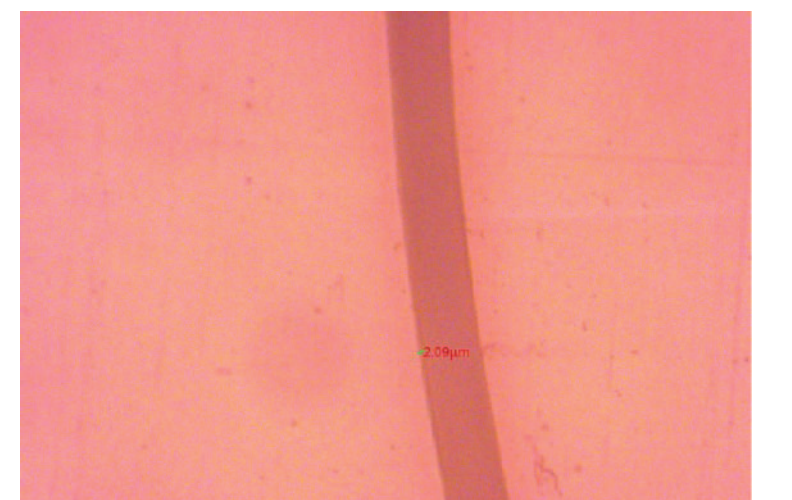


Semiconductor & PCB Materials(FPC, PCB, PI Film, Si)

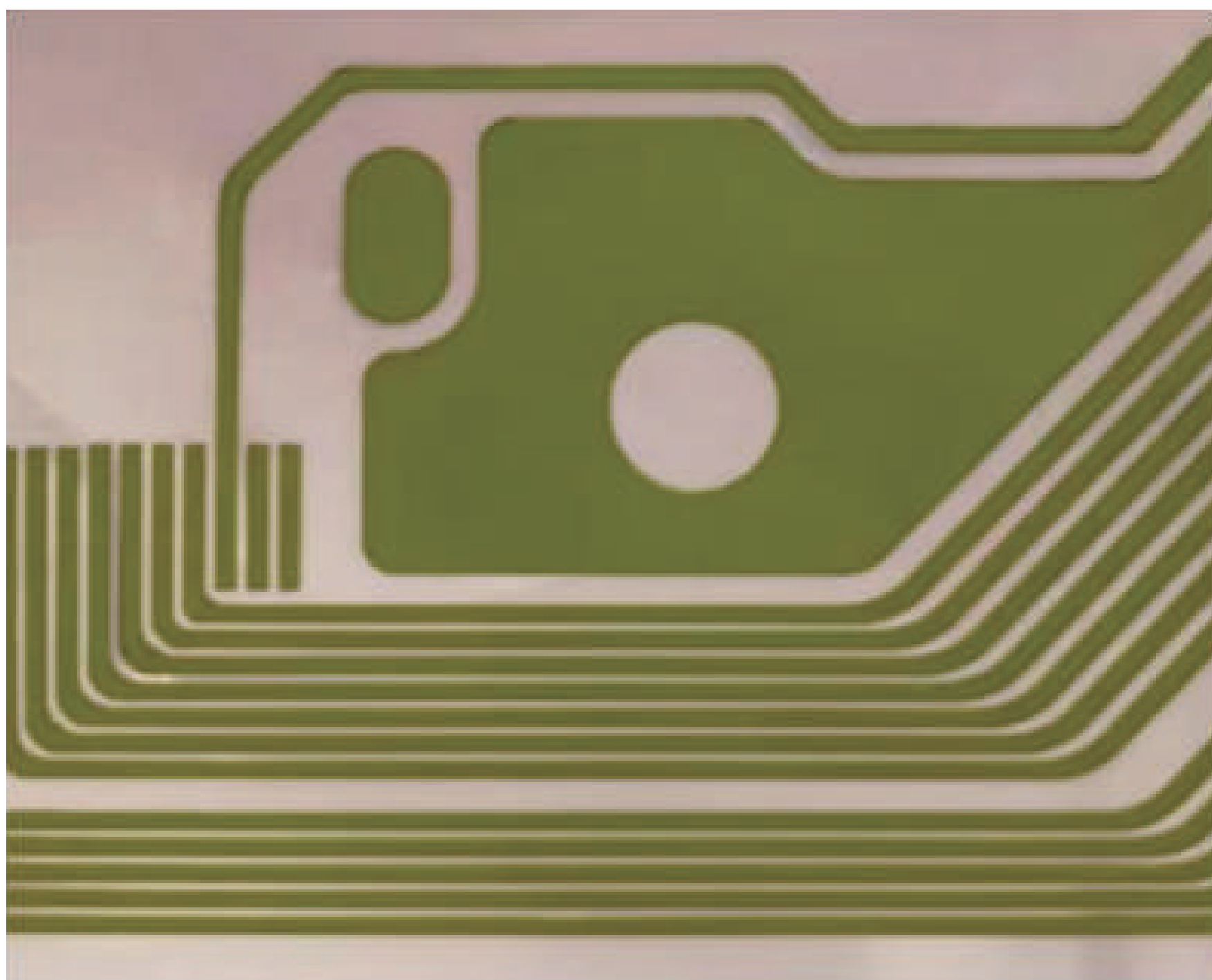
- Minimal mechanical and thermal stress prevents delamination, warping, burrs, and cracks.
- Enables micro-processing at the micron(μm) level.



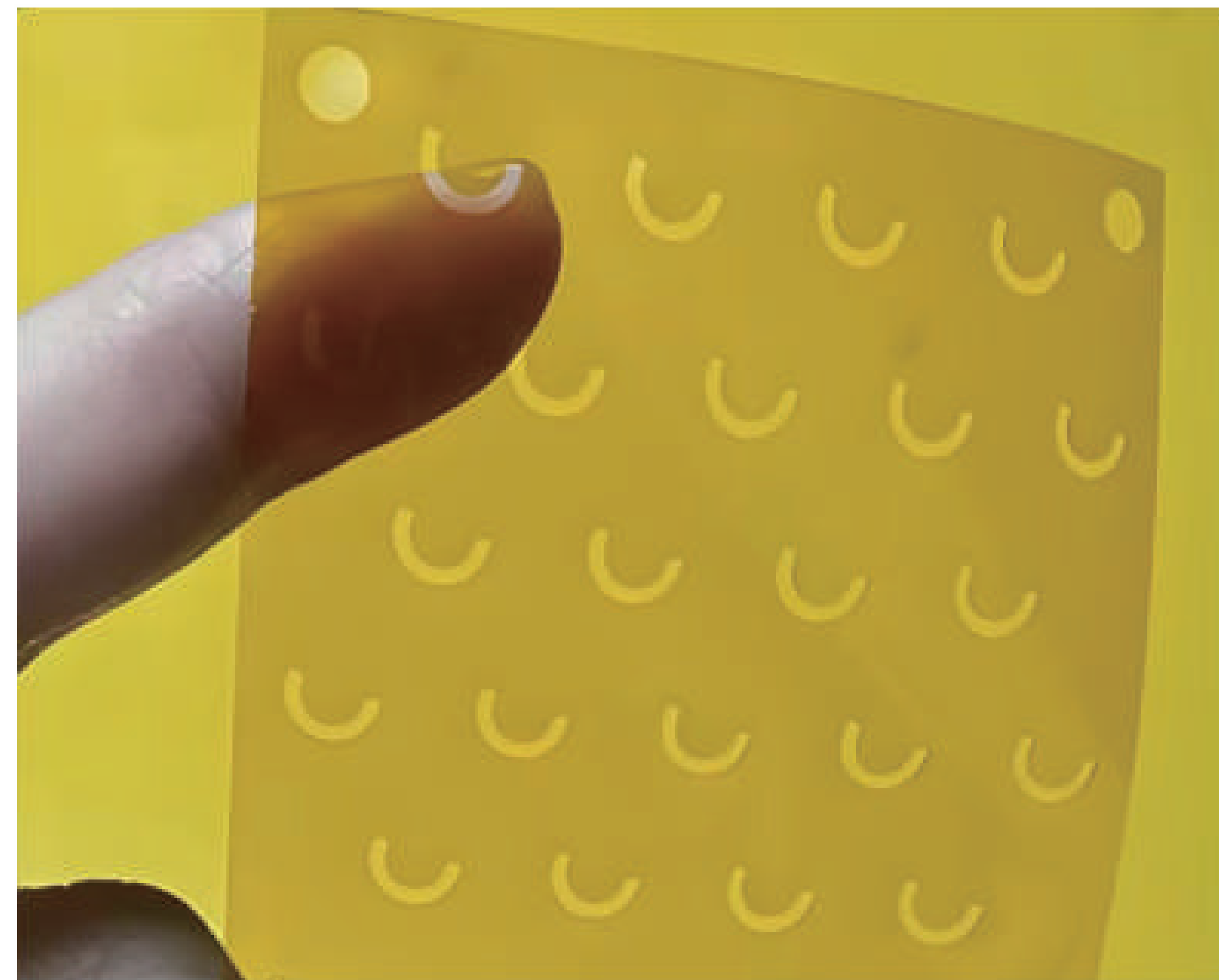
Silicon Wafer Scribing



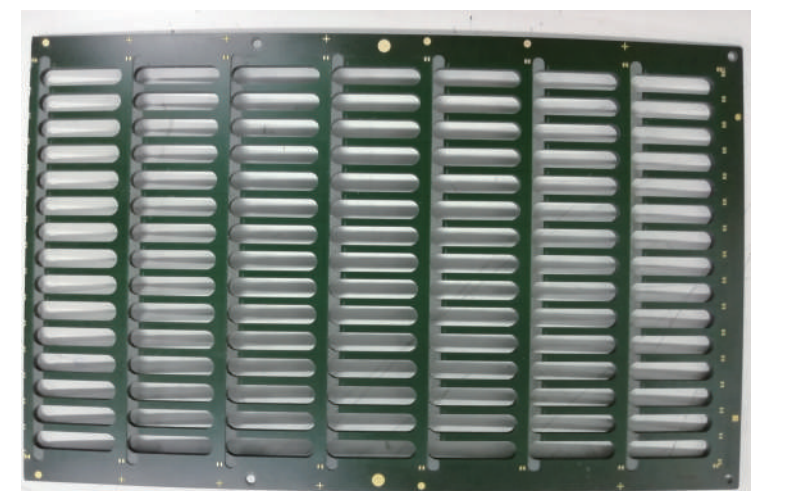
PI Film Cutting($2.09\mu\text{m}$)



FPC Cutting

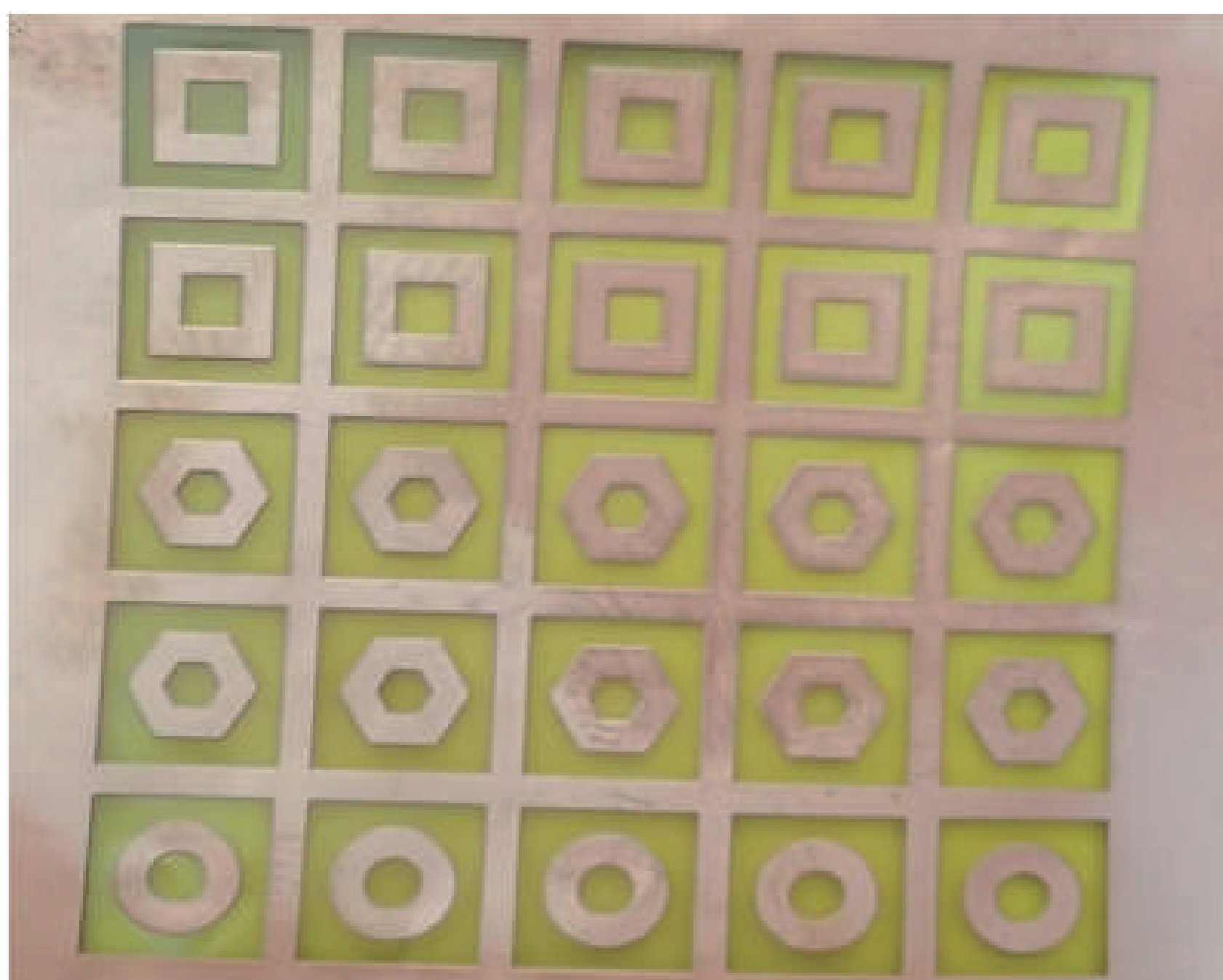


PI Film Cutting

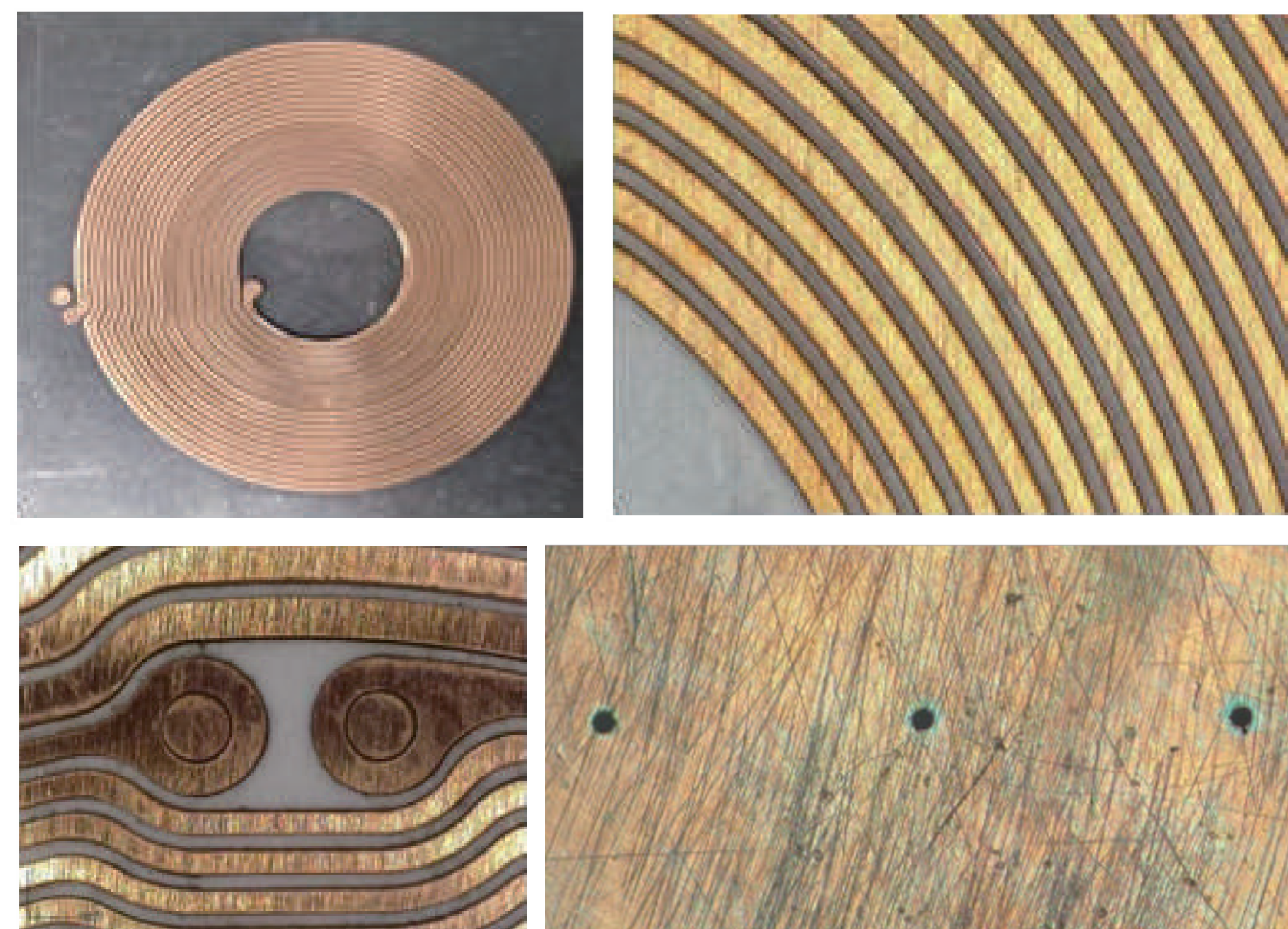


PCB Cutting

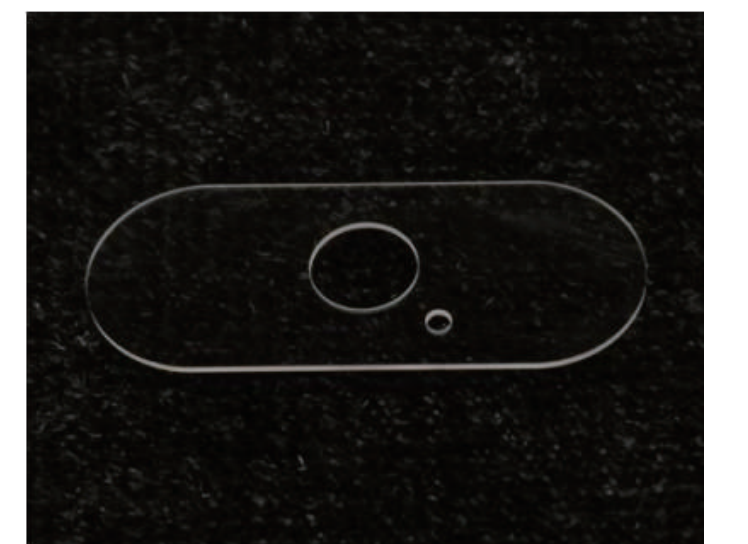
Copper Foils & Composites



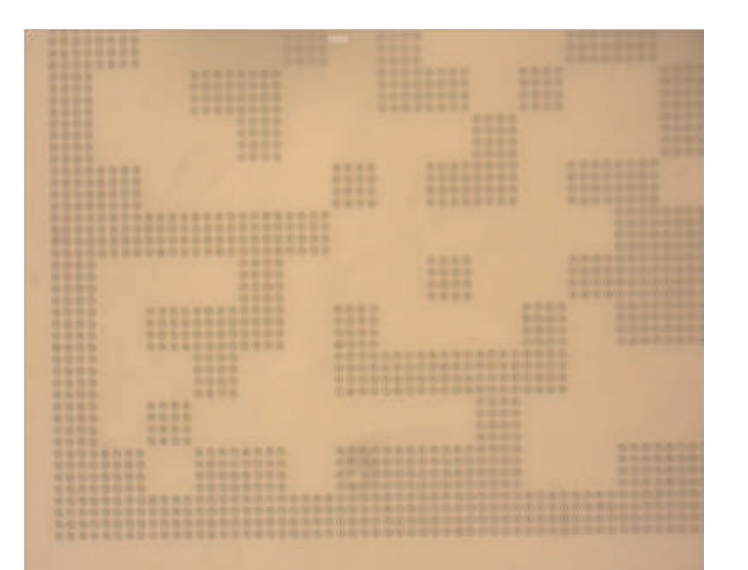
Selective Copper Removal from Composites



Cooper Foil Cutting & Drilling

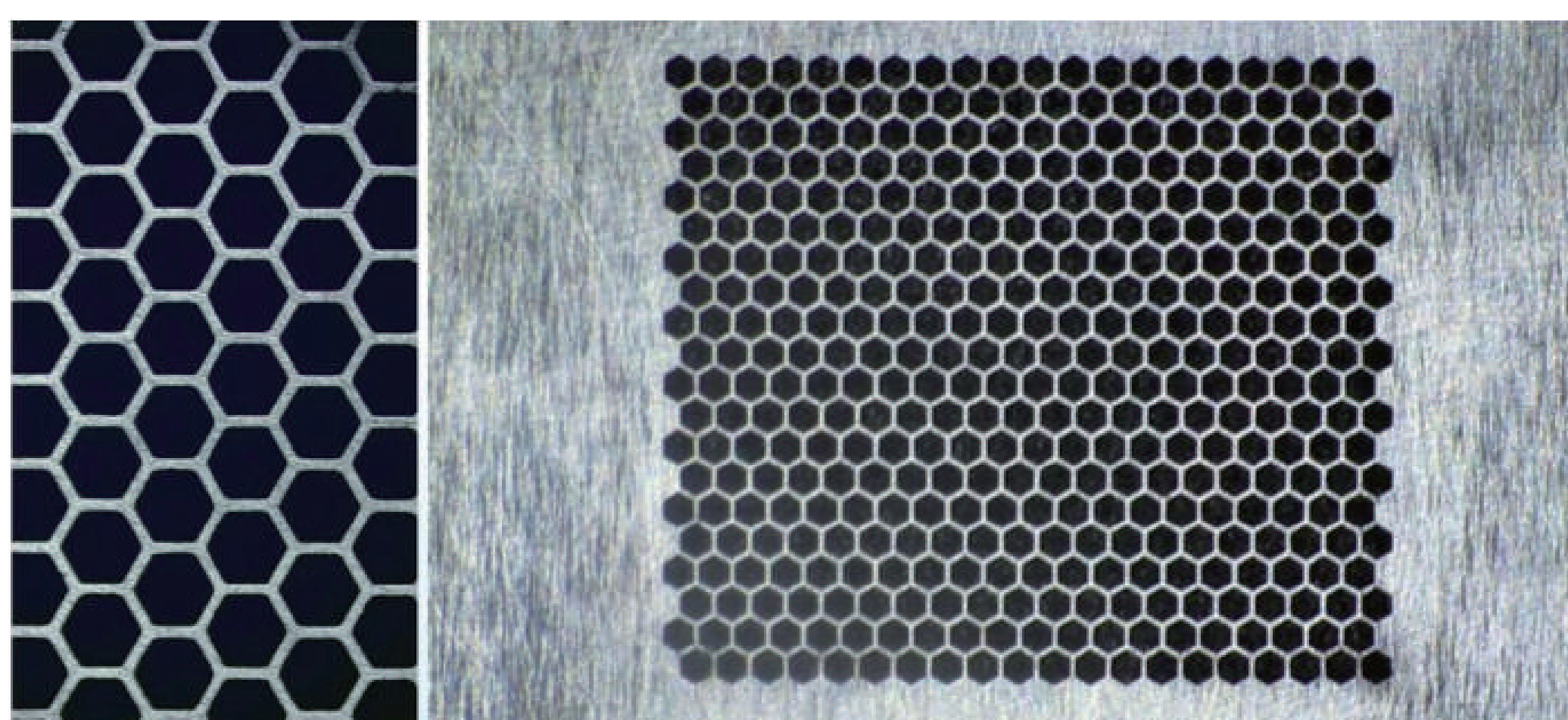


Sapphire Cutting & Drilling

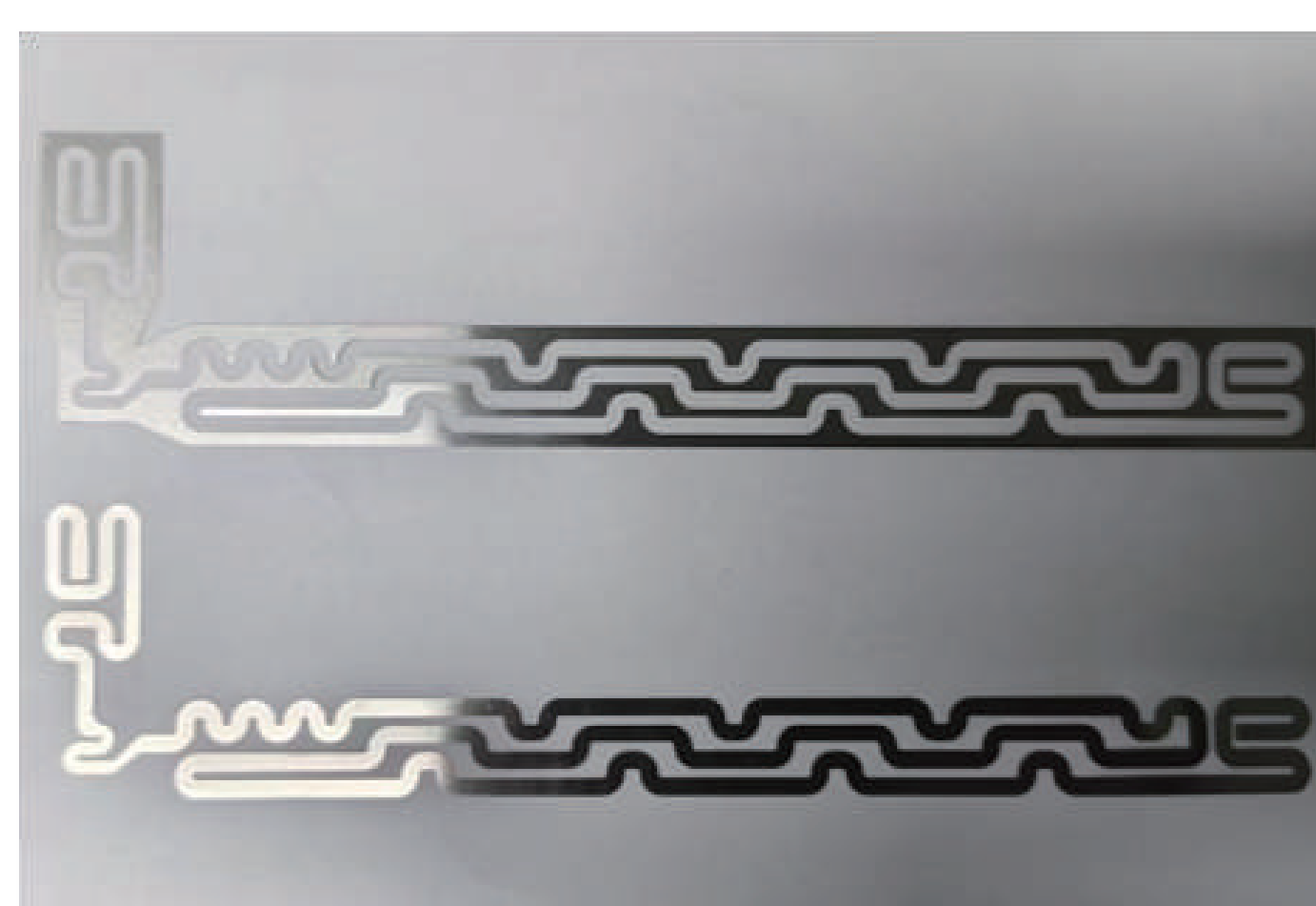


Internal Glass Marking

Stainless Steel



Honeycomb Engraving



Cutting



Color Marking